Title (en)

RESIN COMPOSITION, AND MOLDED ARTICLE PRODUCED FROM THE SAME

Title (de)

HARZZUSAMMENSETUNG UND DARAUS HERGESTELLTER FORMKÖRPER

Title (fr)

COMPOSITION DE RÉSINE ET ARTICLE MOULÉ OBTENU À PARTIR DE CETTE COMPOSITION

Publication

EP 2113532 A4 20120215 (EN)

Application

EP 08710406 A 20080219

Priority

- JP 2008000252 W 20080219
- JP 2007043984 A 20070223
- JP 2007137924 A 20070524

Abstract (en)

[origin: EP2113532A1] Disclosed is a resin composition including a polylactic acid resin (A), a polycarbonate resin (B) and a methyl methacrylate copolymer (C). The mass ratio (A/B) between the resins (A) and (B) is 40/60 to 80/20. The ratio (MFR A /MFR B) between the melt flow rate (MFR A) of the resin (A) and the melt flow rate (MFR B) of the resin (B) is less than 10 at 240°C under a load of 21.2 N. The copolymer (C) is a copolymer between methyl methacrylate and a (meth)acrylic acid ester, and the weight average molecular weight (Mw) of the copolymer (C) is 500,000 or more. The content of the copolymer (C) is 0.1 to 20 parts by mass in relation to 100 parts by mass of the total of the resins (A) and (B).

IPC 8 full level

C08L 67/04 (2006.01); **C08K 5/1515** (2006.01); **C08K 5/29** (2006.01); **C08K 5/353** (2006.01); **C08L 33/14** (2006.01); **C08L 69/00** (2006.01)

CPC (source: EP US)

C08L 67/04 (2013.01 - EP US); **C08L 69/00** (2013.01 - EP US); C08K 5/1515 (2013.01 - EP US); C08K 5/29 (2013.01 - EP US); C08K 5/353 (2013.01 - EP US); C08L 23/0884 (2013.01 - EP US); Y10T 428/254 (2015.01 - EP US)

Citation (search report)

- [I] WO 2006030951 A1 20060323 - TORAY INDUSTRIES [JP], et al & EP 1792941 A1 20070606 - TORAY INDUSTRIES [JP]
- [E] US 2008071038 A1 20080320 - IDO SACHIO [JP]

Cited by

EP2199341A3; EP2199342A3; US8835558B2; WO2014184057A1; US8133943B2; EP2454321B1

Designated contracting state (EPC)

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DOCDB simple family (publication)

EP 2113532 A1 20091104; **EP 2113532 A4 20120215**; **EP 2113532 A8 20100106**; CN 101583667 A 20091118; CN 101583667 B 20121003; EP 2500382 A2 20120919; EP 2500382 A3 20121114; EP 2500382 B1 20140910; JP 2012193370 A 20121011; JP 5409846 B2 20140205; JP WO2008102536 A1 20100527; US 2010028657 A1 20100204; US 8415008 B2 20130409; WO 2008102536 A1 20080828

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